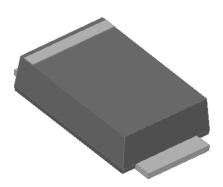
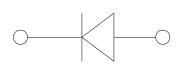




Surface Mount General Purpose Rectifier





Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Part no. with suffix "Q" means AEC-Q101 qualified

Typical Applications

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, automotive and telecommunication.

Mechanical Date

• Package: SMAF

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free

- **Terminals**: Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity: Cathode line denotes the cathode end

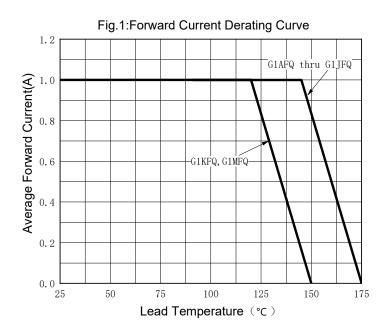
■Maximum Ratings (Ta=25°C Unless otherwise specified)

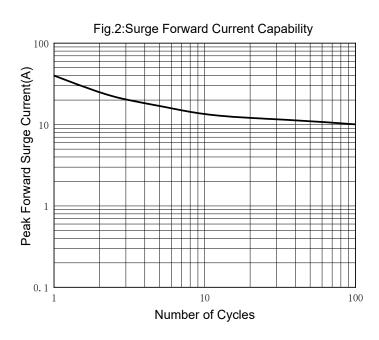
PARAMETER	SYMBOL	UNIT	G1AFQ	G1BFQ	G1DFQ	G1GFQ	G1JFQ	G1KFQ	G1MFQ
Device marking code			G1AF	G1BF	G1DF	G1GF	G1JF	G1KF	G1MF
Repetitive peak reverse voltage	V_{RRM}	٧	50	100	200	400	600	800	1000
Maximum RMS voltage	V _{RMS}	V	35	70	140	280	420	560	700
Average rectified output current @60Hz sine wave, Resistance load	lo	Α	1.0						
Surge(non-repetitive)forward current @ 60Hz half-sine wave,1 cycle, T _J =25°C	I _{FSM}	Α	40						
Current Squared Time @1ms≤t<8.3ms Tj=25℃	l ² t	A ² s	6.64						
Storage temperature	T _{STG}	°	-55 ~+175				-55 ~+150		
Junction temperature	TJ	°C	-55 ~+175 -55 ~+15				+150		

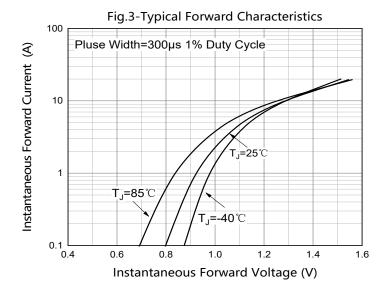
■Electrical Characteristics (Ta=25°C Unless otherwise specified)

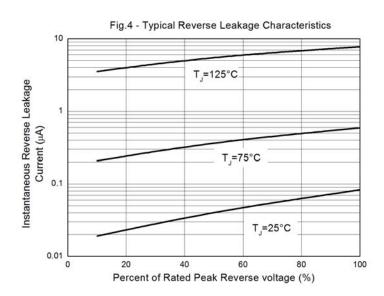
PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	G1AFQ	G1BFQ	G1DFQ	G1GFQ	G1JFQ	G1KFQ	G1MFQ
Maximum instantaneous forward voltage drop per diode	V_{F}	٧	I _{FM} =1.0A	1.1						
Typical junction capacitance	C₃	pF	V _R =4V,1 MHz	16				1	2	
Maximum DC reverse current at		<	Ta=25°C 5		5					
rated DC blocking voltage per diode	per diode I _{RRM} μΑ Ta=125°C				50					

■ Characteristics(Typical)









■ Thermal Characteristics (Ta=25°C Unless otherwise specified)

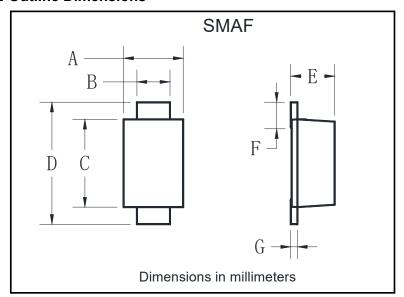
PARAMETER	SYMBOL	UNIT	G1AFQ	G1BFQ	G1DFQ	G1GFQ	G1JFQ	G1KFQ	G1MFQ
Thermal resistance	$R_{\theta J-A}$	°C/W				65 ¹⁾			
Thermal resistance	R _{eJ-L}	C/VV				201)			

Note:

⁽¹⁾ Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 5 mm x 5 mm copper pad areas.

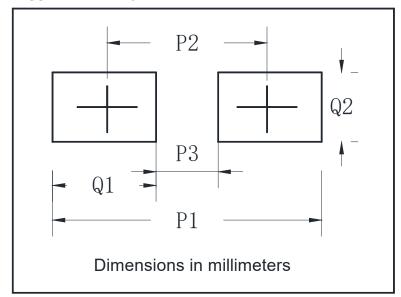


■ Outline Dimensions



SMAF						
Dim	Min	Max				
Α	2.40	2.80				
В	1.35	1.45				
С	3.40	3.60				
D	4.40	4.80				
Е	1.05	1.25				
F	0.50	1.00				
G	0.15	0.31				

■ Suggested pad layout



SMAF				
Dim	Millimeters			
P1	6.50			
P2	4.00			
P3	1.50			
Q1	2.50			
Q2	1.70			

■Ordering Information (Example)

PREFERED	PACKAGE	LINIT WEIGHT(a)		OUTER CARTON	DELIVERY	
P/N	CODE			QUANTITY(pcs)	MODE	
G1AFQ~G1MF0	Q F1	Approximate 0.034	3000	96000	7" reel	



■ Marking Information



Note:

- 1. All marking is at middle of the product body
- 2. All marking is in laser printing
- 3. XXXX is marking code, like G1MFQ marking code is G1MF.4. Body color: Black5. YWW is date code, "Y" is year. "WW" is week.

The 17th week of 2022, date code is 217 The 17th week of 2023, date code is 317



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